

METHOD FOR MANUFACTURING SPACE TRANSFORMER BY USING CARRIER SUBSTRATE MADE FOR CHIP PACKAGE AND PROVIDED WITH ELONGATED CONTACTS

5 ABSTRACT

A space transformer includes a carrier substrate made for a chip package, an insulated layer disposed on the carrier substrate, and a conductive block. The carrier substrate is provided with elongated first and second wires. The first wire has an elongated contact which is longer than the width of the first wire. The insulated layer
10 has a hole corresponding in position to the elongated contact. The conductive block has an elongated connecting column located in the hole and connected with the elongated contact, and a cylindrical contact pad exposed at the outside of the insulated layer, larger-sized than the elongated connecting column and connected with the elongated connecting column. As a result, the cylindrical contact pad has sufficient area and
15 structural strength for contact with a probe needle. The method for manufacturing the space transformer is also disclosed.

Figure 1